



## **AppliedMicro 460GT Power Architecture® Processor is now Qualified to RIOLAB Level 2 and 3 Device Interoperability**

*DIL- Qualification Reports Provide Customers a Greater Level of Confidence When Designing AMCC Processors into a RapidIO System*

**Ottawa, Canada – October 8th, 2009** – RIOLAB™, a division of Fabric Embedded Tools Corporation and the world's only independent RapidIO® interoperability testing facility, today announced AppliedMicro 460GT embedded processor, successfully completed the second and third level of RIOLAB's Device Interoperability Level (DIL) testing.

With speeds of up to 1.0 GHz, support for Serial RapidIO, PCI-Express, Gigabit Ethernet MACs, crypto acceleration, NAND Flash interfaces and low power dissipation, the 460GT embedded processor is ideally suited to a wide range of high-performance applications, including networking and wireless infrastructure. The evaluation kit and reference design are currently available.

"AMCC's completion of DIL 2 and DIL 3 for the 460GT is a significant step in arming OEMs with the kind of detailed reports that are required to help them in their decision of which RapidIO processor to use in their next design." said Jim Parisien, president of Fabric Embedded Tools. "RIOLAB Interoperability reports represent a common independent and unbiased 3<sup>rd</sup> party measure of how a device performs across over 200 hundred RapidIO specification checklist tests."

RIOLAB tests, based on the RapidIO Trade Association's "RapidIO Device Interoperability and Specification Compliance Checklists, 1.3 Spec," address the graduated levels of interoperability that align with the increasing complexity of both the RapidIO specification and the needs of silicon vendors and OEMs.





DIL-1 tests verify device support for initialization, enumeration and basic read and write packet transactions. In DIL-1 testing, the device-under-test is tested against the entire RIOLAB hardware library for both request and response level transactions, with an emphasis on the reliability of interaction between devices. DIL-2 testing is the first level that delves deeper into register and packet protocol compliance under a variety of conditions that are not covered within DIL-1. DIL-3 is the final stage of device interoperability testing as defined within the RapidIO Trade Association specification compliance checklist.

"With the introduction of more and more choices for RapidIO processing endpoints, customers are faced with a growing need for clear, unbiased facts on which to base their decisions.", said Tom Cox, executive director of the RapidIO Trade Association.

"Interoperability Reports from RIOLAB are fundamental tools for OEMs to determine how well a RapidIO device can function in their next system."

#### **About Fabric Embedded Tools**

Fabric Embedded Tools Corporation (<http://www.fetcorp.com>) is the leading provider of RapidIO software, network management and diagnostic tools. The company delivers innovative solutions that shorten product development and testing cycles, and reduce technology risks and time-to-market. Through its unwavering commitment to delivering powerful, time-saving tools and services, excellence in customer support, and strong partner relationships, FET meets the needs of semiconductor vendors, single board computer vendors, and OEMs across the embedded industry.

A division of Fabric Embedded Tools, RIOLAB ([www.riolab.com](http://www.riolab.com)), is a state-of-the-art RapidIO interoperability testing facility that provides device interoperability and specification compliance reports that meet the growing needs of silicon vendors and OEMs designing with RapidIO technology. The lab is the only facility in existence that provides commercial semiconductor vendors, FPGA and ASIC manufacturers with an





unbiased common vehicle for demonstrating device interoperability and specification compliance to the RapidIO standard.

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